PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6099178

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DEFU LIU	04/18/2020
WENHUA YU	04/18/2020
HUAI PENG	04/18/2020
YOUJUN XIONG	04/18/2020

RECEIVING PARTY DATA

Name:	UBTECH ROBOTICS CORP LTD
Street Address:	16TH AND 22ND FLOORS, BLOCK C1, NANSHAN I PARK, NO. 1001 XUEYUAN ROAD, NANSHAN DISTRICT
City:	SHENZHEN
State/Country:	CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16870902

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	2019A208US1
NAME OF SUBMITTER:	RAYMOND J. CHEW
SIGNATURE:	/Raymond J. Chew/
DATE SIGNED:	05/09/2020

Total Attachments: 2

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ASSIGNMENT

WHEREAS Defu Liu; Wenhua Yu; Huai Peng; Youjun Xiong, the assignors, whose mailing address is/are 16th and 22nd Floors, Block C1, Nanshan I Park, No. 1001 Xueyuan Road, Nanshan District, Shenzhen, Guangdong, China,

have invented certain new and useful improvements in an invention relating to and entitled CHARGING MODULE AND ROBOT HAVING THE SAME, the invention, as fully set forth and described in an application for Letters Patent to be filed at the United States Patent and Trademark Office and naming the assignors as inventors and applicants;

AND WHEREAS UBTECH ROBOTICS CORP LTD of China, the assignee, whose mailing address is 16th and 22nd Floors, Block C1, Nanshan I Park, No. 1001 Xueyuan Road, Nanshan District, Shenzhen, Guangdong, China,

is desirous of acquiring the entire right, title and interest in and to said invention, and in and to Any Letters Patent that may be obtained therefor;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00) and other good and valuable consideration, receipt of which is hereby acknowledged, the assignors, do hereby confirm that they have sold, assigned and transferred, and do hereby sell, assign and transfer to the assignee the full and exclusive right to the said invention in the United States and their entire right, title and interest for the United States in and to the invention, together with their entire right, title and interest in and to said application, any and all divisional applications thereof, and any and all Letters Patent of the United States which may issue or be reissued for the invention;

AND the assignors hereby authorize and request the Director of the United States Patent and Trademark Office to issue to said assignee of any and all said Letters Patent not already issued as the assignee of their entire right, title and interest in and to the same, for the sole use and benefit of said assignee, its successors, assigns or legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by the assignors had this assignment and sale not been made.

AND the assignors, on behalf of themselves and their executors and administrators, hereby covenant and agree to do all such lawful acts and things and to execute without further consideration such further lawful assignments, documents, assurances, applications, and other instruments as may reasonably be required by said assignee, its successors, assigns or legal representatives, to obtain any and all Letters Patent of the United States for said invention and vest the same in said assignee, its successors, assigns or legal representatives.

Cont.: Assignment

Defu Liu *[Signature of Inventor]*, SIGNED on this [18th] day of [April], 2020
Defu Liu

Wenhua Yu *[Signature of Inventor]*, SIGNED on this [18th] day of [April], 2020
Wenhua Yu

Huai Peng *[Signature of Inventor]*, SIGNED on this [18th] day of [April], 2020
Huai Peng

Youjun Xiong *[Signature of Inventor]*, SIGNED on this [18th] day of [April], 2020
Youjun Xiong